

Features

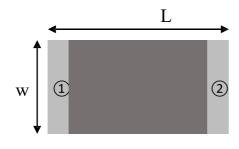
1.Surface Mounted Devices with a small dimension of 1.6 x 0.8 x 0.8 mm meet future miniaturization trend. 2,Embedded and LTCC (low temperature co-fired ceramic) technology is able to integrate with system design as well as beatifying the housing of final product.

3. High stability and low tolerance.

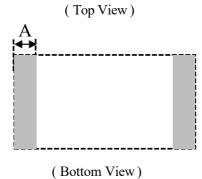
Applications

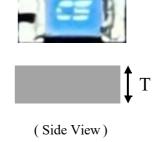
- 1. Bluetooth
- 2. Wireless LAN
- 3. ISM band 2.4GHz wireless applications

Dimensions (Unit: mm)



Number	Terminal Name
1	INPUT
2	NC



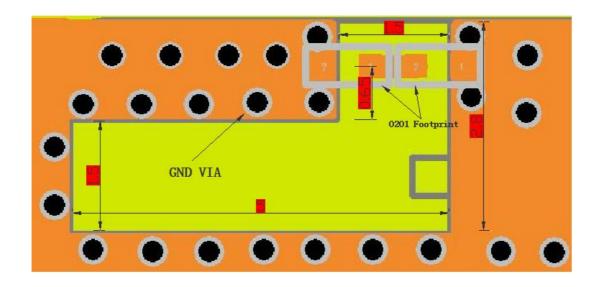


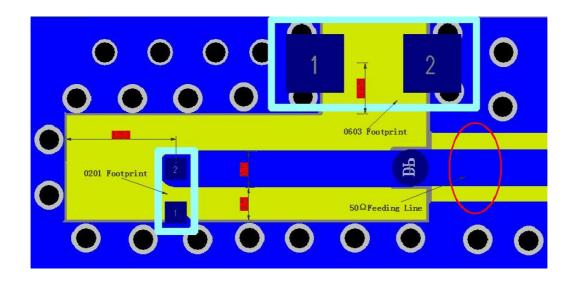
Symbols	L	W	T	A
Dimensions	1.60±0.20	0.80±0.20	0.80±0.20	0.30±0.10

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Evaluation Board and Matching Circuits





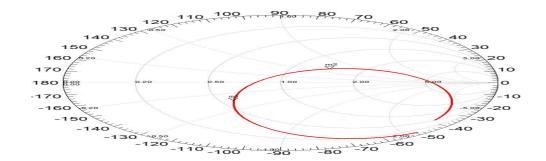
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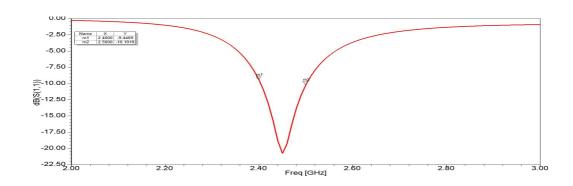


Electrical Characteristics

	Feature	Specification
1	Central frequency	2445MHz
2	Bandwidth	>100MHz
3	Peak gain	1.5dBi
4	VSWR	<2
5	Polarization	Linear
6	Azimuth beamwidth	Omnidirectional
7	Impedance	50 Ω

Characteristic curve



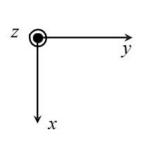


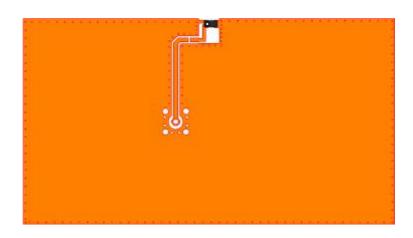
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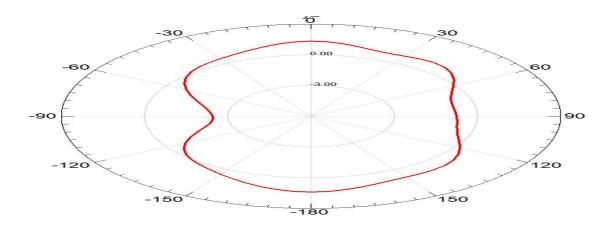
Radiation Pattern

coordinates:

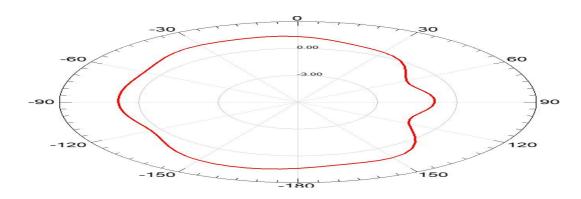




Y-Z Plane



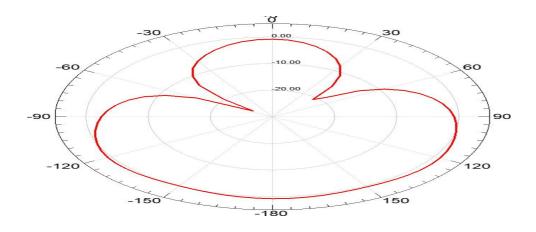
X-Z Plane



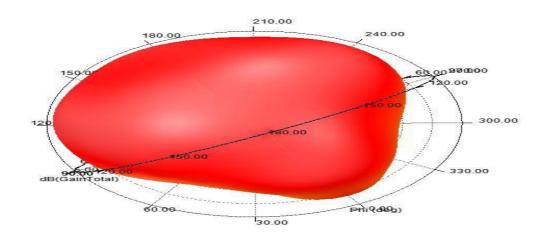
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X-Y Plane



3D Radiation Pattern



Frequency	2400MHz	2450MHz	2500MHz
Avg. gain	-1.14	-0.85	-1.30
Peak gain	1.2	1.4	1.5
Efficiency	77%	82%	78%

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Dependability Test

Test Temperature:

25°C±3°C

Operating Temperature

-25°C~+85°C

Temperature

5~40°C

Relative Humidity

20~70%

Moisture Proof

Temperature: 40±2°C Humidity: 90~95%RH

Duration: 500h

Recovery conditions: Room temperature Recovery Time: 24h (Class1) or 48h (Class2)

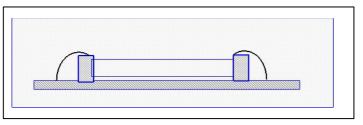
Sol derability

At least 95% of the terminal electrode is covered by new solder. Preheating conditions: 80 to 120°C;

Solder Temperature: 235±5°C Duration: 2±0.5s, Solder Temperature: 245±5°C Duration: 2±0.5s

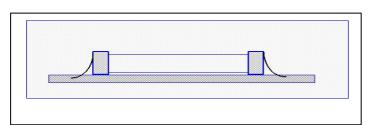
Optimum Solder Amount for Reflow Soldering





Cracks tend to occur due to large stress.

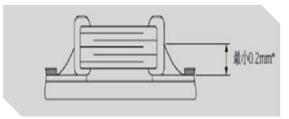
Not enough solder



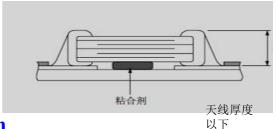
Weak holding force may cause bad connection between the capacitor and PCB.

Recommended Soldering amounts

The optimal solder fillet amounts for re-flow soldering



The optimal solder fillet amounts for wave soldering



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Temperature Cycle Test

10±1S Applied Force: 5N Duration: 10±1S

Preheating conditions: up-category temperature, 1h

Recovery time: 24±1h

Initial Measurement

Cycling Times: 5 times, 1 cycle, 4 steps:

阶段	温度(℃)	时间(分钟)
第1步	下限温度(NPOX7RX7S/X6S/XSR-55)	30
第2步	常温 (+20)	2~3
第3步	上限温度(NMXX7R/X78:+125)	30
第4步	常温 (+20)	2~3

Resistanceto Soldering Heat

Preheating 80 to 120°C; 10~30s. Solder Temperature: 235±5°C Duration: 2±0.5s, Solder Temperature: 245±5°C

Duration:2±0.5s, Preheating100to200°C;10±2min.

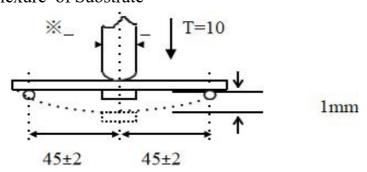
Solder Temperature: 265±5°C Duration: 10±1s

Clean the capacitor with solvent and examine it with a 10X(min.) microscope.

Recovery Time: 24±2h

Recovery condition: Room temperature

Resistance to Flexure of Substrate



Test Board: Al₂O₃ or PCB Warp: 1mm Speed: 0.5mm/sec.

Unit: mm

The measurement should be made with the board in

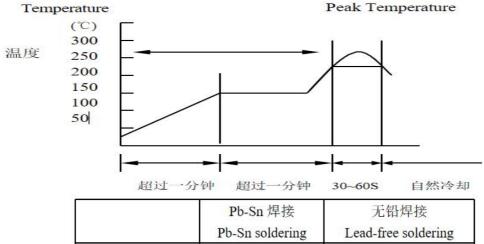
the bending position.

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The temperature profile for soldering

Re-flow soldering

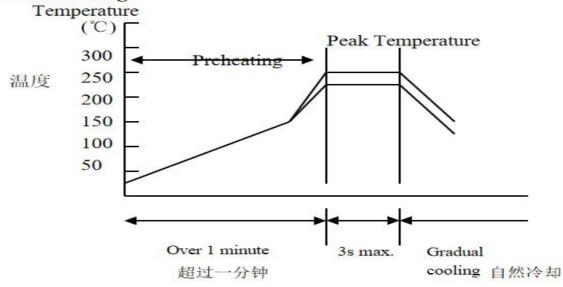


Pb-Sn 焊接 尤铅焊接
Pb-Sn soldering Lead-free soldering

尖峰温度
Peak temperature 230℃~250℃ 240℃~260℃

While in preheating, please keep the temperature difference between soldering temperature and surface temperature of chips as: $T \le 150$ °C.

Wave soldering

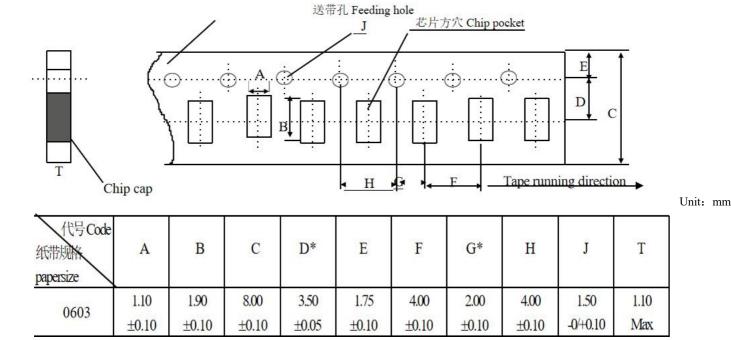


20	Pb-Sn 焊接	无铅焊接	
	Pb-Sn soldering	Lead-free soldering	
尖峰温度 Peak temperature	230℃~260℃	240°C∼270°C	

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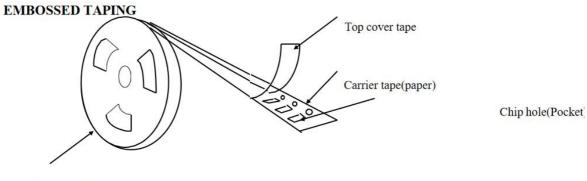


Dimensions of paper taping for 0603types



Reel (4000 pcs/Reel)

Note: The place with means where needs exactly dimensions.



Polystyrene reel

Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition). Temperature $5\sim40\,^{\circ}\text{C}$ /Relative Humidity $20\sim70\%$

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Page 9